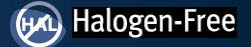


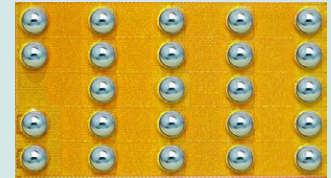
EPC2032 – Enhancement Mode Power Transistor

 V_{DS} , 100 V $R_{DS(on)}$, 4 m Ω I_D , 48 A

Gallium Nitride's exceptionally high electron mobility and low temperature coefficient allows very low $R_{DS(on)}$, while its lateral device structure and majority carrier diode provide exceptionally low Q_G and zero Q_{RR} . The end result is a device that can handle tasks where very high switching frequency, and low on-time are beneficial as well as those where on-state losses dominate.

Maximum Ratings

PARAMETER		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage (Continuous)	100	V
	Drain-to-Source Voltage (up to 10,000 5 ms pulses at 150°C)	120	
I_D	Continuous ($T_A = 25^\circ\text{C}$, $R_{\theta JA} = 7^\circ\text{C/W}$)	48	A
	Pulsed (25°C , $T_{PULSE} = 300 \mu\text{s}$)	340	
V_{GS}	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	
T_J	Operating Temperature	-40 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-40 to 150	



EPC2032 eGaN® FETs are supplied only in passivated die form with solder bumps. Die Size: 4.6 mm x 2.6 mm

- High Speed DC-DC Conversion
- Motor Drive
- Industrial Automation
- Synchronous Rectification
- Class-D Audio

Thermal Characteristics

PARAMETER		TYP	UNIT
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.45	$^\circ\text{C/W}$
$R_{\theta JB}$	Thermal Resistance, Junction-to-Board	3.9	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	45	

Note 1: $R_{\theta JA}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board. See https://epc-co.com/epc/documents/product-training/Appnote_Thermal_Performance_of_eGaN_FETs.pdf for details.

Static Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-to-Source Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 0.8 \text{ mA}$	100			V
I_{DSS}	Drain-Source Leakage	$V_{GS} = 0 \text{ V}$, $V_{DS} = 80 \text{ V}$		0.1	0.6	mA
I_{GSS}	Gate-to-Source Forward Leakage	$V_{GS} = 5 \text{ V}$		1	9	mA
	Gate-to-Source Reverse Leakage	$V_{GS} = -4 \text{ V}$		0.1	0.6	mA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 11 \text{ mA}$	0.8	1.4	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS} = 5 \text{ V}$, $I_D = 30 \text{ A}$		3	4	m Ω
V_{SD}	Source-Drain Forward Voltage	$I_S = 0.5 \text{ A}$, $V_{GS} = 0 \text{ V}$		1.6		V

All measurements were done with substrate connected to source.

Dynamic Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_{ISS}	Input Capacitance	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}$		1270	1530	pF
C_{RSS}	Reverse Transfer Capacitance			14		
C_{OSS}	Output Capacitance			800	1200	
$C_{OSS(ER)}$	Effective Output Capacitance, Energy Related (Note 2)	$V_{DS} = 0\text{ to }50\text{ V}, V_{GS} = 0\text{ V}$		1060		
$C_{OSS(TR)}$	Effective Output Capacitance, Time Related (Note 3)			1320		
R_G	Gate Resistance			0.4		Ω
Q_G	Total Gate Charge	$V_{DS} = 50\text{ V}, V_{GS} = 5\text{ V}, I_D = 30\text{ A}$		12	15	nC
Q_{GS}	Gate-to-Source Charge	$V_{DS} = 50\text{ V}, I_D = 30\text{ A}$		3.1		
Q_{GD}	Gate-to-Drain Charge			2		
$Q_{G(TH)}$	Gate Charge at Threshold			2.3		
Q_{OSS}	Output Charge	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}$		66	100	
Q_{RR}	Source-Drain Recovery Charge			0		

All measurements were done with substrate connected to source.

Note 2: $C_{OSS(ER)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

Note 3: $C_{OSS(TR)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

Figure 1: Typical Output Characteristics at 25°C

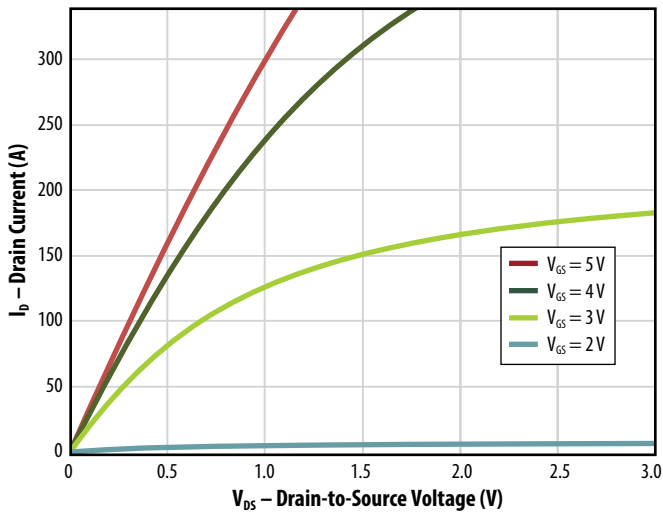


Figure 2: Transfer Characteristics

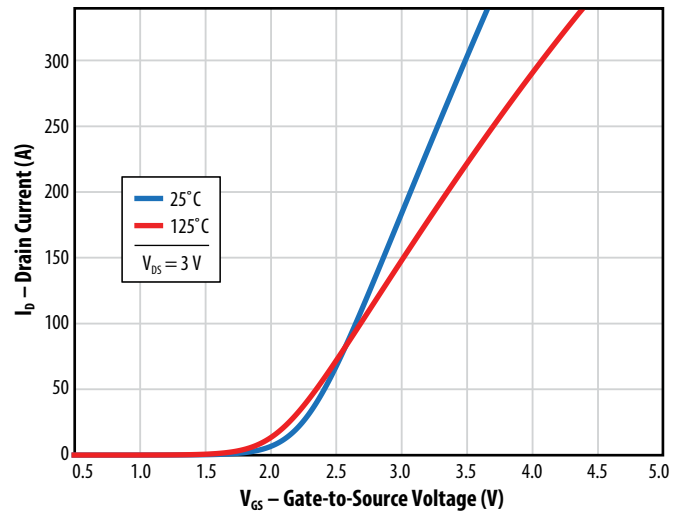


Figure 3: $R_{DS(on)}$ vs. V_{GS} for Various Drain Currents

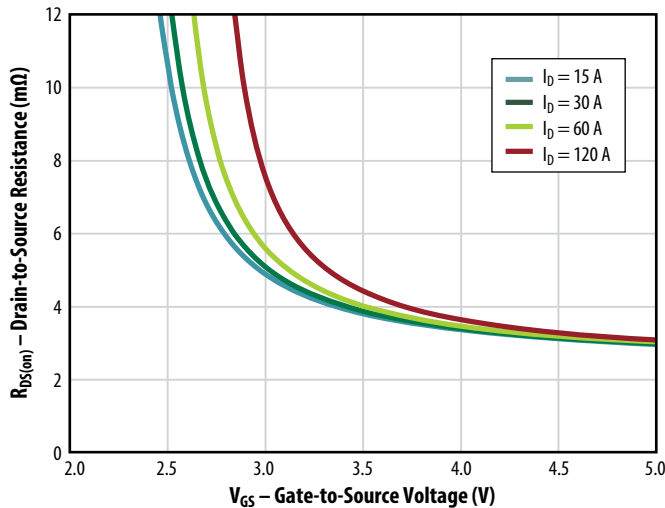


Figure 4: $R_{DS(on)}$ vs. V_{GS} for Various Temperatures

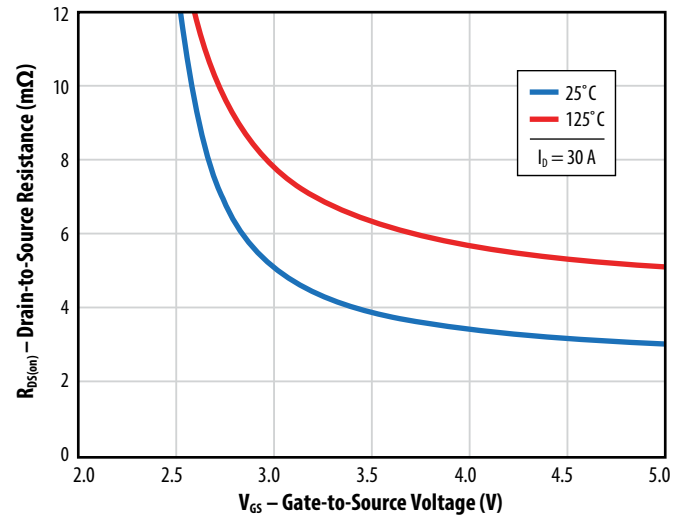


Figure 5a: Capacitance (Linear Scale)

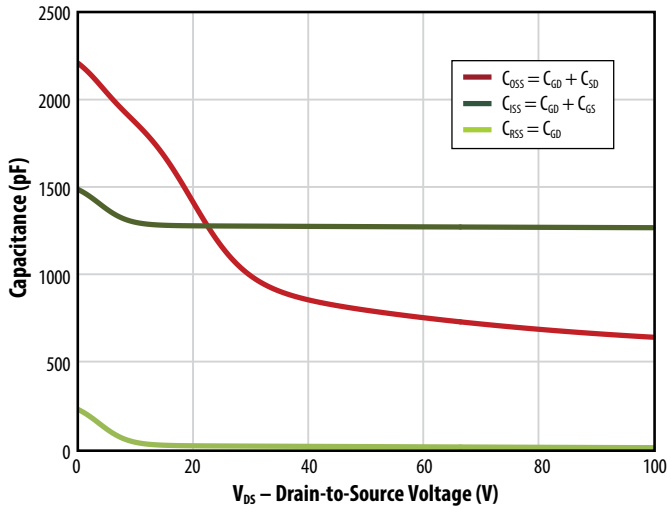


Figure 5b: Capacitance (Log Scale)

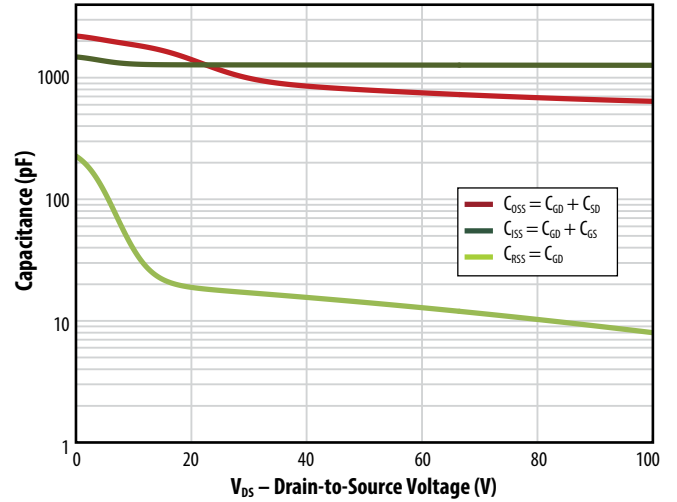


Figure 6: Gate Charge

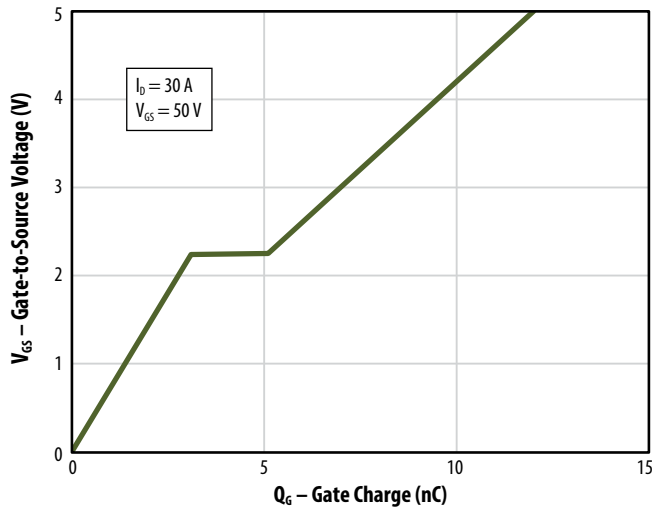


Figure 7: Reverse Drain-Source Characteristics

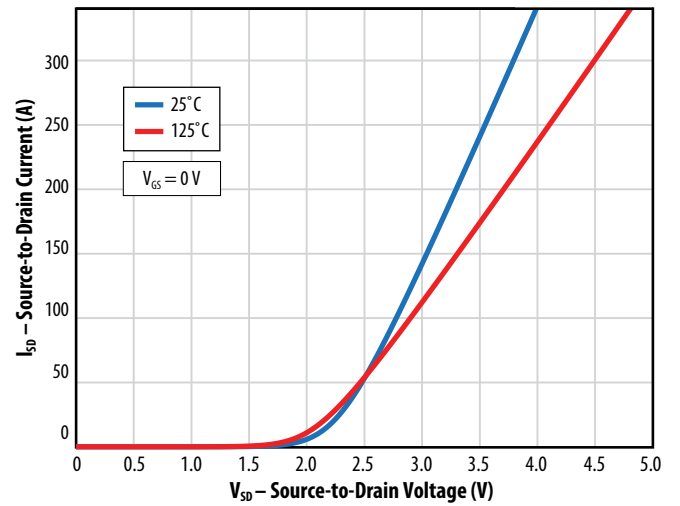


Figure 8: Normalized On-State Resistance vs. Temperature

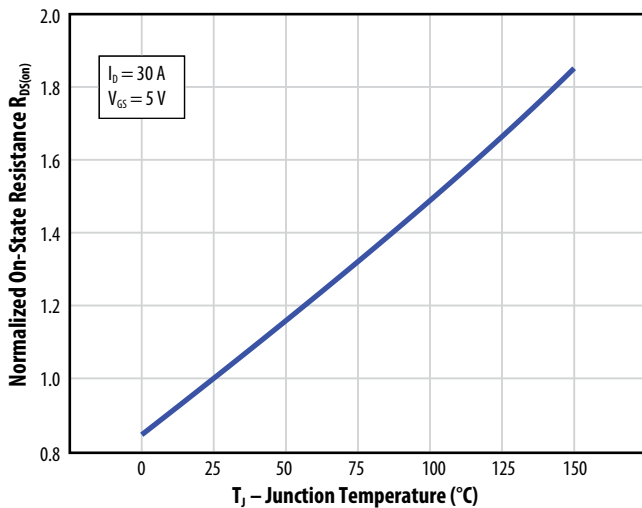
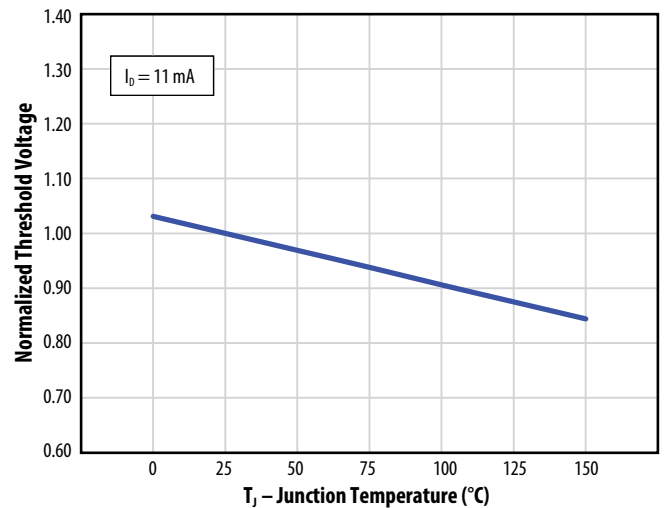


Figure 9: Normalized Threshold Voltage vs. Temperature



All measurements were done with substrate shorted to source.

Figure 10: Gate Leakage Current

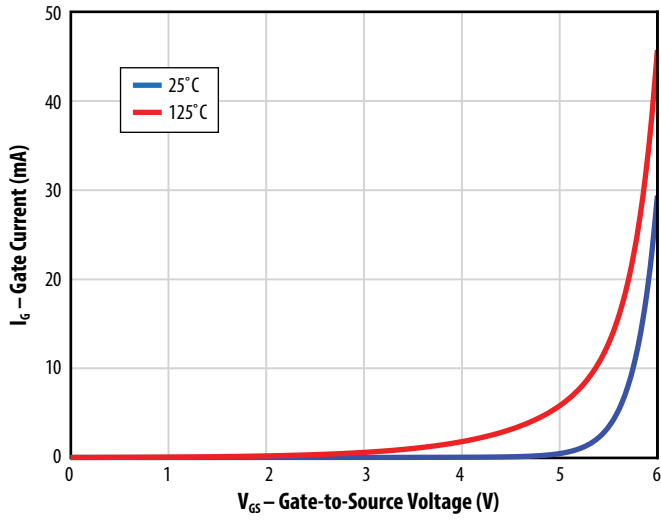


Figure 11: Safe Operating Area

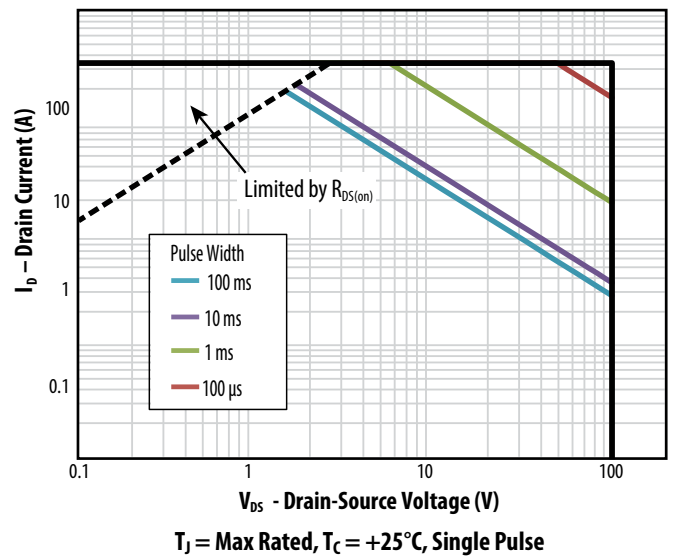
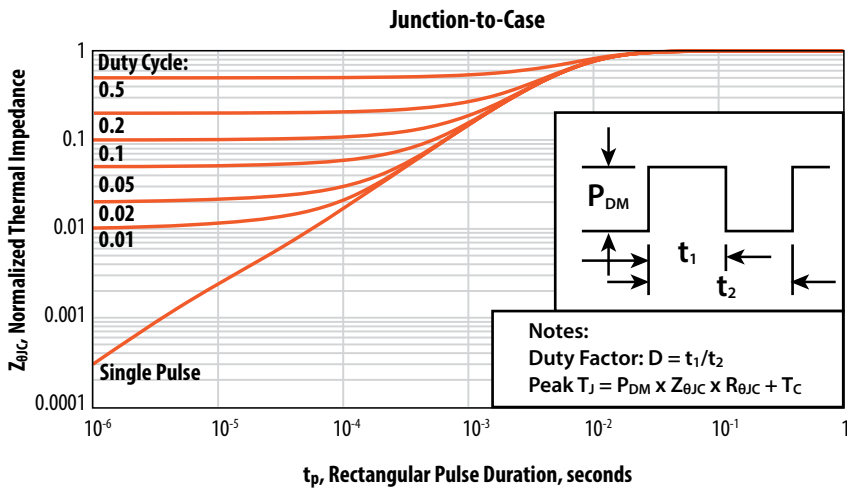
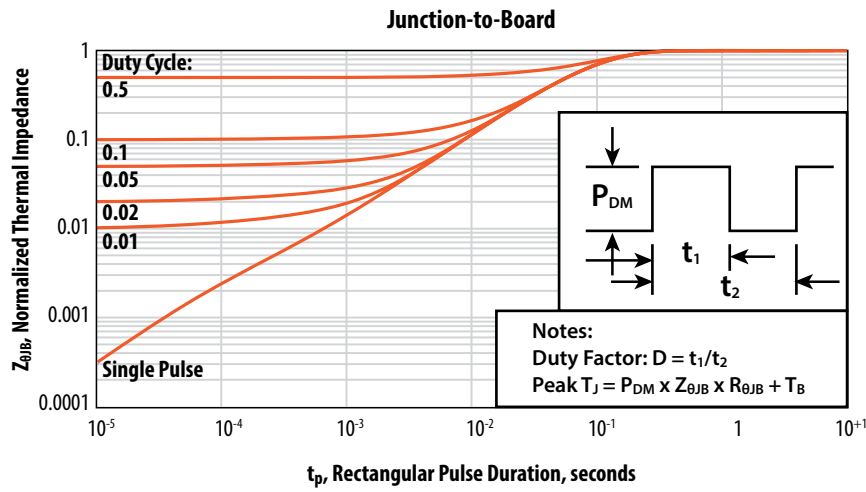
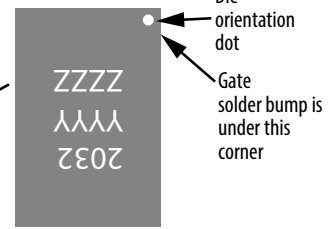
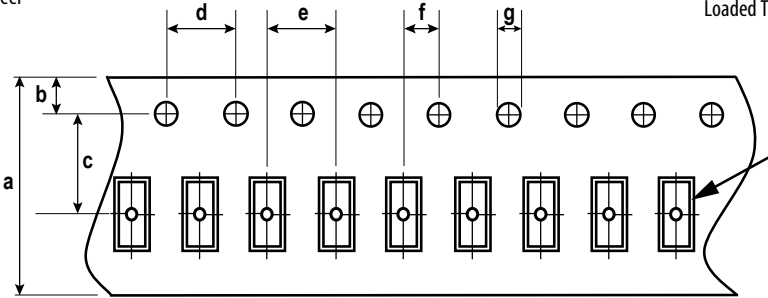
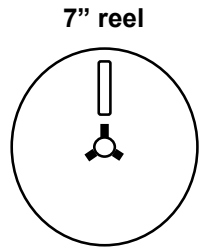


Figure 12: Transient Thermal Response Curves



TAPE AND REEL CONFIGURATION

4 mm pitch, 12 mm wide tape on 7" reel

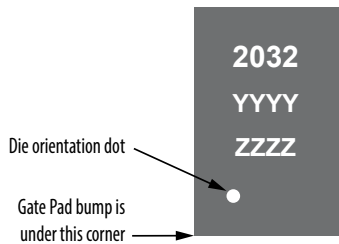


Die is placed into pocket solder bump side down (face side down)

Dimension (mm)	EPC2032 (note 1)		
	target	min	max
a	12.00	11.70	12.30
b	1.75	1.65	1.85
c (note 2)	5.50	5.45	5.55
d	4.00	3.90	4.10
e	4.00	3.90	4.10
f (note 2)	2.00	1.95	2.05
g	1.5	1.5	1.6

Note 1: MSL 1 (moisture sensitivity level 1) classified according to IPC/JEDEC industry standard.
 Note 2: Pocket position is relative to the sprocket hole measured as true position of the pocket, not the pocket hole.

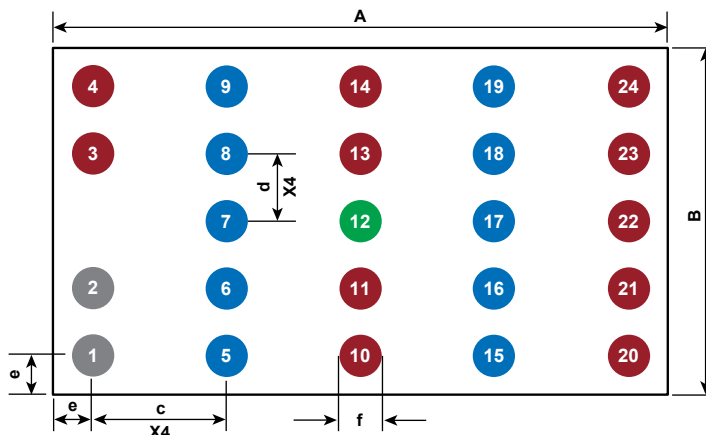
DIE MARKINGS



Part Number	Laser Marking		
	Part # Marking Line 1	Lot_Date Code Marking Line 2	Lot_Date Code Marking Line 3
EPC2032	2032	YYYY	ZZZZ

DIE OUTLINE

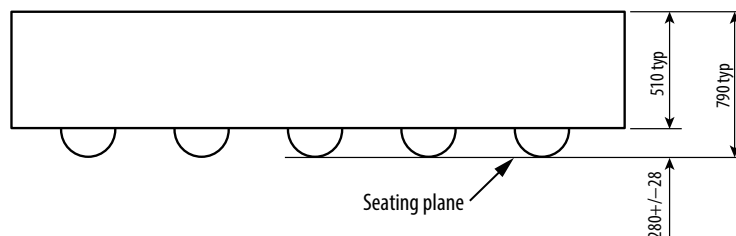
Solder Bump View



DIM	Micrometers		
	MIN	Nominal	MAX
A	4570	4600	4630
B	2570	2600	2630
c	1000	1000	1000
d	500	500	500
e	285	300	315
f	332	369	406

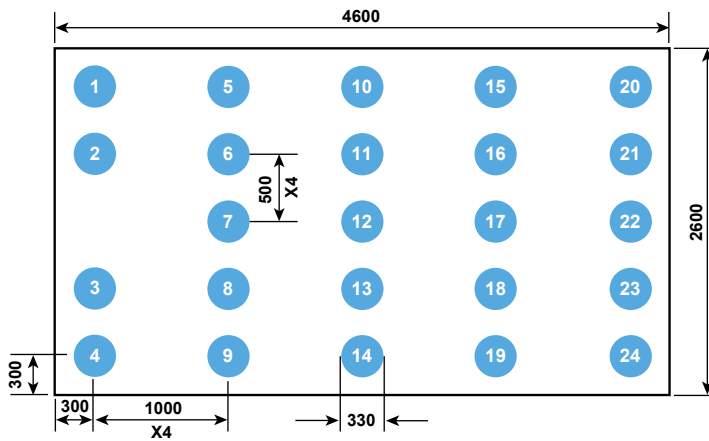
Pads 1 and 2 are Gate;
Pads 5, 6, 7, 8, 9, 15, 16, 17, 18, 19 are Drain;
Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;
Pad 12 is Substrate*

Side View



*Substrate pin should be connected to Source

RECOMMENDED LAND PATTERN
(units in μm)



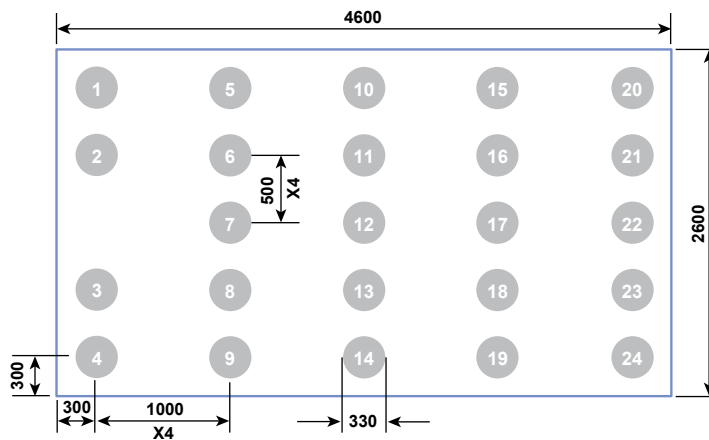
Land pattern is solder mask defined
Solder mask opening is 330 μm
It is recommended to have on-Cu trace PCB vias

Pads 1 and 2 are Gate;
Pads 5, 6, 7, 8, 9, 15, 16, 17, 18, 19 are Drain;
Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;
Pad 12 is Substrate*

*Substrate pin should be connected to Source

RECOMMENDED STENCIL DRAWING
(units in μm)

Option 1 : Intended for use with SAC305 Type 4 solder.

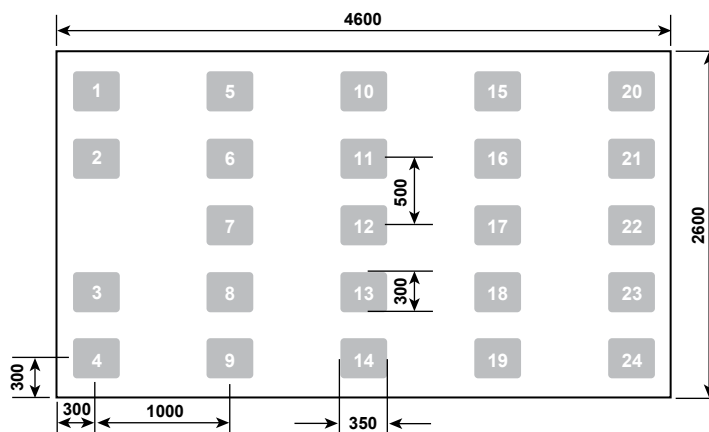


Recommended stencil should be 4 mil (100 μm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at
<https://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx>

RECOMMENDED STENCIL DRAWING
(units in μm)

Option 2 : Intended for use with SAC305 Type 3 solder.



Recommended stencil should be 4 mil (100 μm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at
<https://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx>

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